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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/572,730	03/21/2006	Hiroshi Oji	40404.30/tt	6903
54068	7590	01/02/2009		
ROHM CO., LTD. C/O KEATING & BENNETT, LLP 1800 Alexander Bell Drive SUITE 200 Reston, VA 20191			EXAMINER HUYNH, ANDY	
			ART UNIT 2818	PAPER NUMBER
			NOTIFICATION DATE 01/02/2009	DELIVERY MODE ELECTRONIC

**Please find below and/or attached an Office communication concerning this application or proceeding.**

The time period for reply, if any, is set in the attached communication.

Notice of the Office communication was sent electronically on above-indicated "Notification Date" to the following e-mail address(es):

JKEATING@KBIPLAW.COM  
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<b>Office Action Summary</b>	<b>Application No.</b> 10/572,730	<b>Applicant(s)</b> OJI, HIROSHI	
	<b>Examiner</b> ANDY HUYNH	<b>Art Unit</b> 2818	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

### Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

### Status

- 1) ☒ Responsive to communication(s) filed on 22 October 2008.
- 2a) ☐ This action is **FINAL**.                      2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

### Disposition of Claims

- 4) ☒ Claim(s) 1-5 is/are pending in the application.
- 4a) Of the above claim(s) 3-5 is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 1 and 2 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

### Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☒ The drawing(s) filed on 21 March 2006 is/are: a) ☒ accepted or b) ☐ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

### Priority under 35 U.S.C. § 119

- 12) ☒ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☒ All    b) ☐ Some \*    c) ☐ None of:
1. ☒ Certified copies of the priority documents have been received.
2. ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

### Attachment(s)

- |  |   |
|--|---|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892)            | 4) <input type="checkbox"/> Interview Summary (PTO-413)           |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948)   | Paper No(s)/Mail Date. _____                                      |
| 3) <input checked="" type="checkbox"/> Information Disclosure Statement(s) (PTO/SB/08) | 5) <input type="checkbox"/> Notice of Informal Patent Application |
| Paper No(s)/Mail Date <u>02/21/2007, 03/21/2006</u> .                                  | 6) <input type="checkbox"/> Other: _____                          |

## **DETAILED ACTION**

### ***Election/Restrictions***

This is responsive to Applicant's the Response to Restriction Requirement and Election of Species Requirement filed October 22, 2008. In view of the Response, Applicant has elected without traverse Group I and Species II (Fig. 3), including Claims **1 and 2**, for examination on the merits is acknowledged. Accordingly, Claims **3-5** are withdrawn from consideration as being directed to a non-elected invention. See 37 CFR 35 § 1.142(b) and MPEP § 821.03. Applicant has the right to file a divisional application covering the subject matter of the non-elected Claims **3-5**.

### ***Priority***

Acknowledgment is made of applicant's claim for foreign priority under 35 U.S.C. 119(a)-(d) based on an application filed in JAPAN, 2004-187240 on 06/25/2004.

### ***Information Disclosure Statement***

This office acknowledges receipt of the following items from the applicant: Information Disclosure Statement(s) (IDS(s)) filed on 03/21/2006 and 02/21/2007 made of record. The references cited on the PTOL 1449 form have been considered.

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***Claim Rejections - 35 USC § 103***

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

The factual inquiries set forth in *Graham v. John Deere Co.*, 383 U.S. 1, 148 USPQ 459 (1966), that are applied for establishing a background for determining obviousness under 35 U.S.C. 103(a) are summarized as follows:

1. Determining the scope and contents of the prior art.
2. Ascertaining the differences between the prior art and the claims at issue.
3. Resolving the level of ordinary skill in the pertinent art.
4. Considering objective evidence present in the application indicating obviousness or nonobviousness.

Claim 1 is rejected under 35 U.S.C. 103(a) as being unpatentable over JP03-276730, Applicant's submitted prior art (ASPA), in view of US 6,849,908 B2 to Hirano et al. hereinafter "Hirano."

JP03-276730 (ASPA) discloses in Fig. 1 a semiconductor device, comprising:

- a well 8 of a first conductive p<sup>+</sup> type formed in an upper layer of a substrate 1;
- a low-concentration layer 7 of the first conductive p- type having a lower impurity concentration than the well 8, the low-concentration layer 7 being formed in an extreme surface layer of a channel portion of the well 8;
- a gate dielectric layer 2 formed on the low-concentration layer 7;

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a gate electrode 3 formed on the gate dielectric layer 2; and  
source/drain regions 6 of a second conductive n<sup>+</sup> type formed in an upper layer of the well 8, the source/drain regions 6 sandwiching the low-concentration layer 7 (see English Abstract).

JP03-276730 does not explicitly disclose a gate dielectric layer being a high-k gate dielectric layer having a higher dielectric constant than a silicon oxide film. Hirano teaches in Fig. 4 a similar semiconductor device comprising, inter alia, a high-k gate dielectric layer/a metal silicate layer 12a having a higher dielectric constant than a silicon oxide film to suppress leakage current flowing through the gate dielectric film (col. 1, lines 33-41, lines 49-50, and col. 5, line 62-col. 6, line 26). It would have been obvious to one having ordinary skill in the art at the time of the invention was made to form a high-k gate dielectric layer/a metal silicate layer served as a gate dielectric film having a higher dielectric constant than a silicon oxide film, as taught by Hirano in the semiconductor device as disclosed by JP03-276730 in order to suppress leakage current flowing through the gate dielectric film (see Hirano, col. 6, lines 24-26).

Claim 2 is rejected under 35 U.S.C. 103(a) as being unpatentable over US 7,087,969 B2 to Nishiyama et al. hereinafter "Nishiyama" in view of JP03-276730, Applicant's submitted prior art (ASPA).

Nishiyama discloses in Fig. 1 and related texts as set forth in col. 4, line 45-col. 5, line 30, a complementary semiconductor device having a n-type circuit region 3 and a p-type circuit region 5, comprising:

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a p-type well 9 formed in an upper layer of a substrate 1 of the n-type circuit region 3;  
a n-type well 19 formed in an upper layer of the substrate 1 of the p-type circuit region 5;  
a high-k gate dielectric layer 13 made of hafnium silicate (HfSiON) including boron (B) formed on the p-type well 9 and a high-k gate dielectric layer 23 made of hafnium silicate (HfSiON) not substantially including boron (B) formed on the n-type well 19, it is inhering that the high-k gate dielectric layers 13/23 made of hafnium silicate (HfSiON) including boron (B)/hafnium silicate (HfSiON) not substantially including boron (B) having a higher dielectric constant than a silicon oxide film;

a gate electrode 15/25 formed on the high-k gate dielectric layer 13/23;  
n-type source/drain regions 11 formed in an upper layer of the p-type well 9; and  
p-type source/drain regions 21 formed in an upper layer of the n-type well 19.

Nishiyama does not explicitly disclose a p-type low-concentration layer formed in an extreme surface layer of a channel portion of the p-type well, the p-type low-concentration layer having a lower impurity concentration than the p-type well, a n-type low-concentration layer formed in an extreme surface layer of a channel portion of the n-type well, the n-type low-concentration having a lower impurity concentration than the n-type well, the n-type source/drain regions sandwiching the p-type low-concentration layer, and the p-type source/drain regions sandwiching the n-type low-concentration layer. JP03-276730 (ASPA) discloses in Fig. 1 a semiconductor device, comprising: a well 8 of a first conductive p<sup>+</sup> type formed in an upper layer of a substrate 1; a low-concentration layer 7 of the first conductive p-type having a lower impurity concentration than the well 8, the low-concentration layer 7 being formed in an extreme surface layer of a channel portion of the well 8; a gate dielectric layer 2 formed on the low-

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concentration layer 7; a gate electrode 3 formed on the gate dielectric layer 2; and source/drain regions 6 of a second conductive  $n^+$  type formed in an upper layer of the well 8, the source/drain regions 6 sandwiching the low-concentration layer 7 (see English Abstract). It would have been obvious to one having ordinary skill in the art at the time of the invention was made to provide a low-concentration layer formed in an extreme surface layer of a channel portion of the well having a lower impurity concentration than the well, as taught by JP03-276730 in the semiconductor device as disclosed by Nishiyama to arrive the claimed limitations, a p-type low-concentration layer formed in an extreme surface layer of a channel portion of the p-type well, the p-type low-concentration layer having a lower impurity concentration than the p-type well, a n-type low-concentration layer formed in an extreme surface layer of a channel portion of the n-type well, the n-type low-concentration having a lower impurity concentration than the n-type well, the n-type source/drain regions sandwiching the p-type low-concentration layer, and the p-type source/drain regions sandwiching the n-type low-concentration layer in order to decrease a threshold voltage and to suppress a short-channel effect (see JP03-276730, English Abstract).

### ***Conclusion***

A shortened statutory period for response to this action is set to expire 3 (three) months and 0 (zero) day from the day of this letter. Failure to respond within the period for response will cause the application to become abandoned (see M.P.E.P 710.02(b)).

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Andy Huynh, (571) 272-1781. The examiner can normally be

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reached on Monday-Friday from 6:30 AM to 3:00 PM. If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Steven Loke can be reached on (571) 272-1657. The Fax number for the organization where this application or proceeding is assigned is (571) 273-8300.

Any inquiry of a general nature or relating to the -status of this application or proceeding should be directed to the receptionist whose phone number is (703) 308-0956.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

/Andy Huynh/  
Primary Examiner, Art Unit 2818